

SN54AHCT132, SN74AHCT132 QUADRUPLE POSITIVE-NAND GATES WITH SCHMITT-TRIGGER INPUTS

SCLS366G – MAY 1997 – REVISED APRIL 2002

- Inputs Are TTL-Voltage Compatible
- Operation From Very Slow Input Transitions
- Temperature-Compensated Threshold Levels
- High Noise Immunity
- Same Pinouts as 'AHCT00
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description

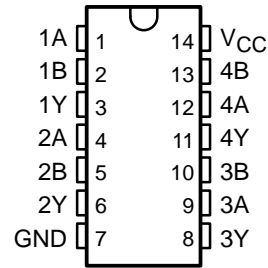
The 'AHCT132 devices are quadruple positive-NAND gates.

These devices perform the Boolean function $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

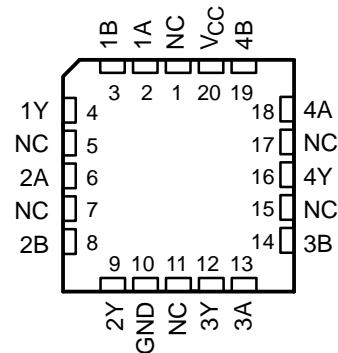
Each circuit functions as a NAND gate, but because of the Schmitt action, it has different input threshold levels for positive- and negative-going signals.

These circuits are temperature compensated and can be triggered from the slowest of input ramps and still give clean jitter-free output signals.

SN54AHCT132 . . . J OR W PACKAGE
SN74AHCT132 . . . D, DB, DGV, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHCT132 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

| T _A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|---------------|-----------------|-----------------------|------------------|
| –40°C to 85°C | PDIP – N | Tube | SN74AHCT132N | SN74AHCT132N |
| | SOIC – D | Tube | SN74AHCT132D | AHCT132 |
| | | Tape and reel | SN74AHCT132DR | |
| | SOP – NS | Tape and reel | SN74AHCT132NSR | AHCT132 |
| | SSOP – DB | Tape and reel | SN74AHCT132DBR | HB132 |
| | TSSOP – PW | Tape and reel | SN74AHCT132PWR | HB132 |
| TVSOP – DGV | Tape and reel | SN74AHCT132DGVR | HB132 | |
| –55°C to 125°C | CDIP – J | Tube | SNJ54AHCT132J | SNJ54AHCT132J |
| | CFP – W | Tube | SNJ54AHCT132W | SNJ54AHCT132W |
| | LCCC – FK | Tube | SNJ54AHCT132FK | SNJ54AHCT132FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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 **TEXAS
INSTRUMENTS**

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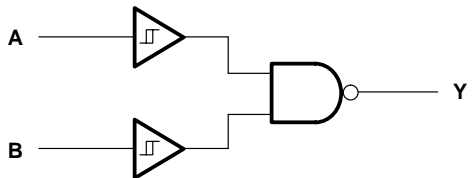
**SN54AHCT132, SN74AHCT132
 QUADRUPLE POSITIVE-NAND GATES
 WITH SCHMITT-TRIGGER INPUTS**

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FUNCTION TABLE
 (each gate)

| INPUTS | | OUTPUT |
|--------|---|--------|
| A | B | Y |
| H | H | L |
| L | X | H |
| X | L | H |

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|--|----------------------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | -0.5 V to 7 V |
| Output voltage range, V_O (see Note 1) | -0.5 V to $V_{CC} + 0.5$ V |
| Input clamp current, I_{IK} ($V_I < 0$) | -20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) | ± 20 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ± 25 mA |
| Continuous current through V_{CC} or GND | ± 50 mA |
| Package thermal impedance, θ_{JA} (see Note 2): | |
| D package | 86°C/W |
| DB package | 96°C/W |
| DGV package | 127°C/W |
| N package | 80°C/W |
| NS package | 76°C/W |
| PW package | 113°C/W |
| Storage temperature range, T_{stg} | -65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Note 3)

| | | SN54AHCT132 | | SN74AHCT132 | | UNIT |
|-----------------|--------------------------------|-------------|-----------------|-------------|-----------------|------|
| | | MIN | MAX | MIN | MAX | |
| V _{CC} | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| V _I | Input voltage | 0 | 5.5 | 0 | 5.5 | V |
| V _O | Output voltage | 0 | V _{CC} | 0 | V _{CC} | V |
| I _{OH} | High-level output current | | -8 | | -8 | mA |
| I _{OL} | Low-level output current | | 8 | | 8 | mA |
| T _A | Operating free-air temperature | -55 | 125 | -40 | 85 | °C |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | | SN54AHCT132 | | SN74AHCT132 | | UNIT |
|---|---|-----------------|-----------------------|-----|------|-------------|-----|-------------|------|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V _{T+} Positive-going input threshold voltage | | 4.5 V | 0.9 | | 1.9 | 0.9 | 1.9 | 0.9 | 1.9 | V |
| | | 5.5 V | 1 | | 2.1 | 1 | 2.1 | 1 | 2.1 | |
| V _{T-} Negative-going input threshold voltage | | 4.5 V | 0.5 | | 1.5 | 0.5 | 1.5 | 0.5 | 1.5 | V |
| | | 5.5 V | 0.6 | | 1.7 | 0.6 | 1.7 | 0.6 | 1.7 | |
| ΔV _T Hysteresis (V _{T+} - V _{T-}) | | 4.5 V | 0.3 | | 1.4 | 0.3 | 1.4 | 0.3 | 1.4 | V |
| | | 5.5 V | 0.3 | | 1.5 | 0.3 | 1.5 | 0.3 | 1.5 | |
| V _{OH} | I _{OH} = -50 μA | 4.5 V | 4.4 | 4.5 | | 4.4 | | 4.4 | | V |
| | I _{OH} = -8 mA | | 3.94 | | | 3.8 | | 3.8 | | |
| V _{OL} | I _{OL} = 50 μA | 4.5 V | | | 0.1 | | | 0.1 | | V |
| | I _{OL} = 8 mA | | | | 0.36 | | 0.5 | | 0.44 | |
| I _I | V _I = 5.5 V or GND | 0 V to 5.5 V | | | ±0.1 | | ±1* | | ±1 | μA |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 5.5 V | | | 2 | | 20 | | 20 | μA |
| ΔI _{CC} † | One input at 3.4 V, Other inputs at V _{CC} or GND | 5.5 V | | | 1.35 | | 1.5 | | 1.5 | mA |
| C _i | V _I = V _{CC} or GND | 5 V | | 2 | 10 | | | | 10 | pF |

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | $T_A = 25^\circ\text{C}$ | | | SN54AHCT132 | | SN74AHCT132 | | UNIT |
|-----------|--------------|-------------|----------------------|--------------------------|-----|-----|-------------|-----|-------------|-----|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t_{PLH} | A or B | Y | $C_L = 15\text{ pF}$ | 5.5* | 8* | 1* | 9* | 1 | 9 | ns | |
| t_{PHL} | | | | 4.5* | 6* | 1* | 7* | 1 | 7 | | |
| t_{PLH} | A or B | Y | $C_L = 50\text{ pF}$ | 6.5 | 9 | 1 | 10 | 1 | 10 | ns | |
| t_{PHL} | | | | 5.5 | 7 | 1 | 8 | 1 | 8 | | |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 4)

| PARAMETER | SN74AHCT132 | | | UNIT |
|--|-------------|------|-----|------|
| | MIN | TYP | MAX | |
| $V_{OL(P)}$ Quiet output, maximum dynamic V_{OL} | 0.5 | 0.8 | | V |
| $V_{OL(V)}$ Quiet output, minimum dynamic V_{OL} | -0.28 | -0.8 | | V |
| $V_{OH(V)}$ Quiet output, minimum dynamic V_{OH} | 5 | | | V |
| $V_{IH(D)}$ High-level dynamic input voltage | 2 | | | V |
| $V_{IL(D)}$ Low-level dynamic input voltage | | | 0.8 | V |

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

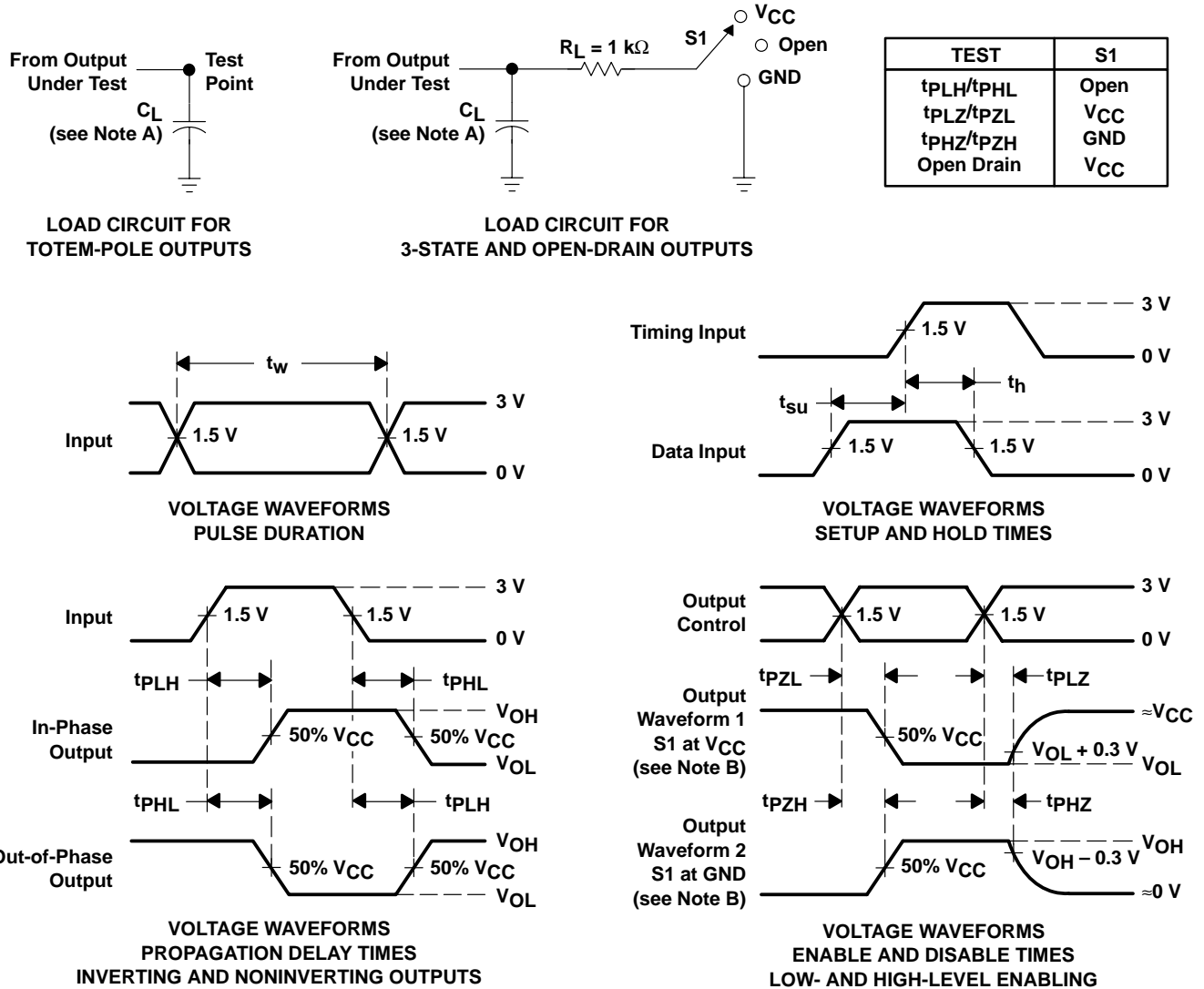
| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|--|-----------------------------|-----|------|
| C_{pd} Power dissipation capacitance | No load, $f = 1\text{ MHz}$ | 15 | pF |

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN74AHCT132D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT132 | Samples |
| SN74AHCT132DBR | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB132 | Samples |
| SN74AHCT132DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT132 | Samples |
| SN74AHCT132DGVR | ACTIVE | TVSOP | DGV | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB132 | Samples |
| SN74AHCT132DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT132 | Samples |
| SN74AHCT132DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT132 | Samples |
| SN74AHCT132DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT132 | Samples |
| SN74AHCT132N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | SN74AHCT132N | Samples |
| SN74AHCT132NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT132 | Samples |
| SN74AHCT132PWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB132 | Samples |
| SN74AHCT132PWRE4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB132 | Samples |
| SN74AHCT132PWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB132 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AHCT132DBR | SSOP | DB | 14 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74AHCT132DGVR | TVSOP | DGV | 14 | 2000 | 330.0 | 12.4 | 6.8 | 4.0 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74AHCT132DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74AHCT132NSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74AHCT132PWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AHCT132DBR | SSOP | DB | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74AHCT132DGVR | TVSOP | DGV | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74AHCT132DR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN74AHCT132NSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74AHCT132PWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |

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